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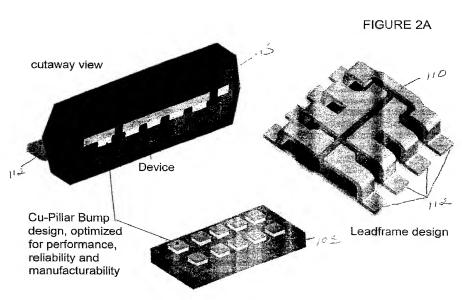
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(57) Abstract: There is provided herein exemplary embodiments of a semiconductor device constructed in accordance with the present invention. The device comprises: a semiconductor chip (105) having a lateral power transistor formed therein. The chip (105) has an upper surface and source, drain and gate contact terminals on the upper surface thereof. Each of the source, drain and ate contact terminals have a conductive ball (106) or pillar thereon A metal lead frame (110) spans the upper surface of the chip, the metal lead frame(110) being in electrical contact with the conductive balls or pillar bumps. A capsule (115) encases the chip(105) and at least a portion of the metal lead frame(110) such that opposite ends of the metal lead frame protrudes from opposite sides of the capsule (115).



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Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched				
Electronic data base consulted during the international search (name of data base and, where practicable, search terms used) EAST				
C. DOCUMENTS CONSIDERED TO BE RELEVANT				
Category *	Citation of document, with indication, where appropriate, of the relevant passages		assages	Relevant to claim No.
x	US 5,945,730 A (SICARD et al) 31 August 1999 (31.08.1999), column 2, lines 37-50,			1-25
A	column 3, line 13, Figure 2. US 6,861,702 A (KITAMURA) 1 March 2005 (01.03.2005)			
A	US 6,674,157 A (LANG) 6 January 2004 (06.01.2004)			
Further	documents are listed in the continuation of Box C.	See patent famil	y annex.	
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